

# MODEL BB110RC

**Resistor capacitor network**  
**Thick film resistors**  
**Ceramic chip capacitors**



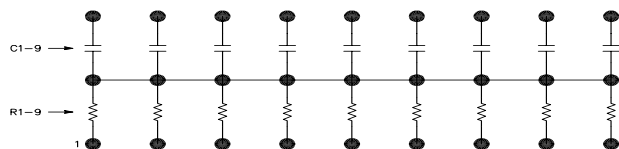
## DISCRIPTION

Model BB110RC is designed for terminating high-speed memory buses. Ideally suited for local decoupling of data line drivers. These specialty networks employ solder balls for surface mount flip chip attachment. Their unique construction yields extremely low capacitance and inductance parasitics critical for these high-speed applications.

## FEATURES

- Integrated resistor and capacitor network
- High density packaging
- High temperature solder balls
- Industry standard ball diameter and pitch
- Excellent high frequency performance

## SCHEMATIC



C1-9 = 0.1uF  
R1-9 = 50 Ω

## ELECTRICAL<sup>1</sup>

Resistance Tolerance	± 1%
Capacitance Tolerance	± 10%
Capacitor Type	X5R
Capacitor Maximum Voltage	10 volts
TCR	200 ppm/°C
Operating Temperature Range	-55°C to +85°C
Maximum Resistor Power	0.05 watts at 70°C
Package Power Rating	1.0 watt @ 70°C

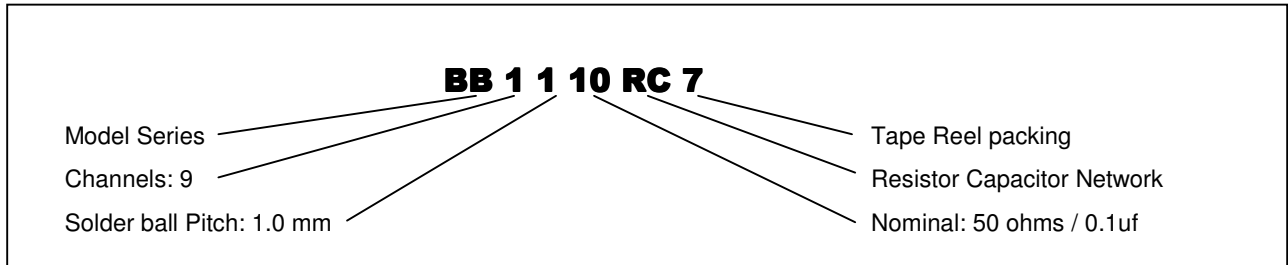
<sup>1</sup> Specifications subject to change without notice.

# MODEL BB1110RC

## MECHANICAL

Solder Ball Finish	SnPb 10/90
Solder Ball Co-planarity	0.15 mm
Substrate Material	Al <sub>2</sub> O <sub>3</sub>
Resistor Material	Cermet

## ORDERING INFORMATION<sup>2</sup>

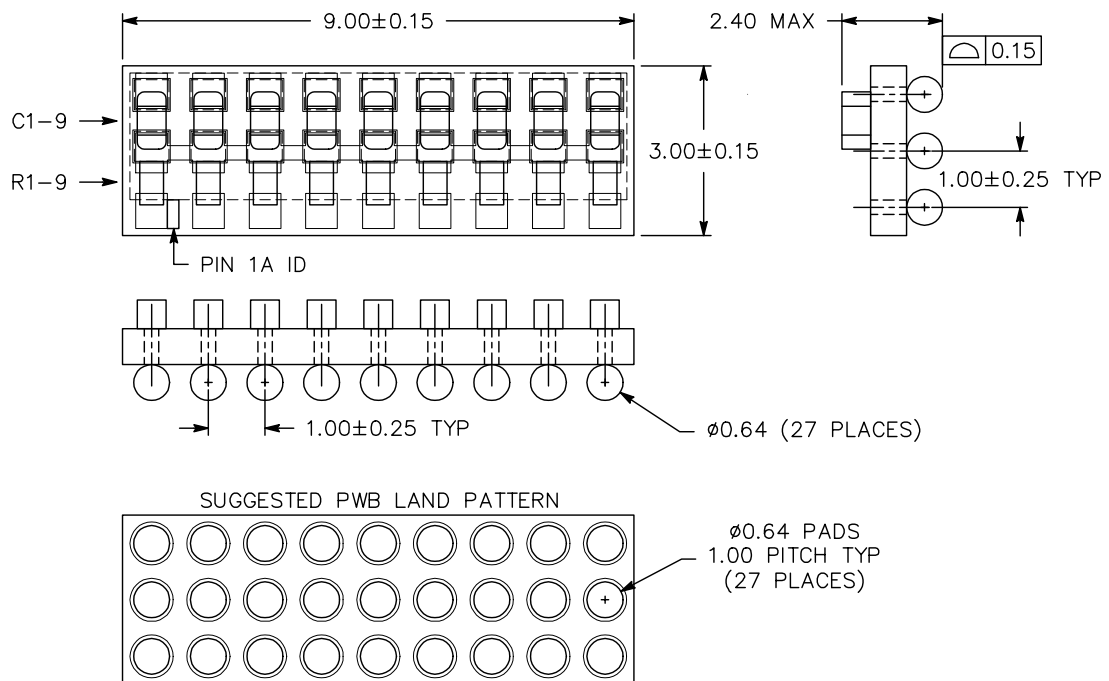


## PACKING INFORMATION

Tape reel suffix (also reel size in inches)	7	13
Part count/reel	750	3000

## OUTLINE DRAWING

Units: mm



<sup>2</sup> Contact our customer service for custom designs and features.